

### **NCE N-Channel Super Trench II Power MOSFET**

#### **Description**

The series of devices uses **Super Trench II** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of  $R_{DS(ON)}$  and  $Q_g$ . This device is ideal for high-frequency switching and synchronous rectification.

#### **Application**

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

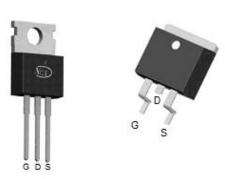
#### **General Features**

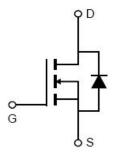
- $V_{DS}$  =100V, $I_D$  =110A  $R_{DS(ON)}$ =5.4m $\Omega$  , typical (TO-220)@  $V_{GS}$ =10V  $R_{DS(ON)}$ =5.2m $\Omega$  , typical (TO-263)@  $V_{GS}$ =10V
- Excellent gate charge x R<sub>DS(on)</sub> product(FOM)
- Very low on-resistance R<sub>DS(on)</sub>
- 175 °C operating temperature
- Pb-free lead plating

100% UIS TESTED! 100% ΔVds TESTED!

**TO-220** 

TO-263





**Schematic Diagram** 

#### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCEP055N10M	NCEP055N10M	TO-220	-	-	-
NCEP055N10MD	NCEP055N10MD	TO-263	-	-	-

#### Absolute Maximum Ratings (T<sub>c</sub>=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	100	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	I <sub>D</sub>	110	Α
Drain Current-Continuous(T <sub>C</sub> =100 °C)	I <sub>D</sub> (100°C)	84	Α
Pulsed Drain Current	I <sub>DM</sub>	440	Α
Maximum Power Dissipation	P <sub>D</sub>	150	W
Derating factor		1.0	W/℃
Single pulse avalanche energy (Note 5)	E <sub>AS</sub>	680	mJ
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55 To 175	$^{\circ}$



## NCEP055N10M, NCEP055N10MD

#### **Thermal Characteristic**

Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup>	R <sub>eJC</sub>	1.0	°C/W
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## **Electrical Characteristics (Tc=25℃ unless otherwise noted)**

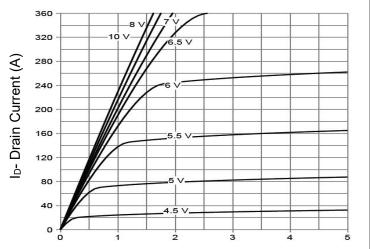
Parameter	Symbol	Condition		Min	Тур	Max	Unit
Off Characteristics				•	•		•
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250µA		100		-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =100V,V <sub>GS</sub> =0V		-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V		-	-	±100	nA
On Characteristics (Note 3)				•	•		•
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250µA		2.0	3.0	4.0	V
Davis Course On Otata Basistana		V <sub>GS</sub> =10V, I <sub>D</sub> =55A	TO-220	-	5.4	5.7	mΩ
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>		TO-263		5.2	5.7	mΩ
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> =5V,I <sub>D</sub> =55A			60	-	S
Dynamic Characteristics (Note4)				•	•		•
Input Capacitance	C <sub>lss</sub>	- V <sub>DS</sub> =50V,V <sub>GS</sub> =0V, - F=1.0MHz		-	3850	-	PF
Output Capacitance	Coss			-	410	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>			-	20	-	PF
Switching Characteristics (Note 4)				•	•		
Turn-on Delay Time	t <sub>d(on)</sub>	$V_{DD}$ =50V, $I_{D}$ =55A $V_{GS}$ =10V, $R_{G}$ =1.6 $\Omega$		-	21	-	nS
Turn-on Rise Time	t <sub>r</sub>			-	61	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>			-	40	-	nS
Turn-Off Fall Time	t <sub>f</sub>			-	12	-	nS
Total Gate Charge	Qg	V <sub>DS</sub> =50V,I <sub>D</sub> =55A, V <sub>GS</sub> =10V		-	72	-	nC
Gate-Source Charge	Q <sub>gs</sub>			-	21		nC
Gate-Drain Charge	$Q_{gd}$			-	22		nC
Drain-Source Diode Characteristics	- '						
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =50A		-		1.2	V
Diode Forward Current (Note 2)	Is			-	-	100	Α
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25°C, I <sub>F</sub> = I <sub>S</sub>		-	67	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs <sup>(Note3)</sup>		-	137	-	nC

#### Notes:

- ${\it 1. Repetitive \ Rating: Pulse \ width \ limited \ by \ maximum \ junction \ temperature.}$
- 2. Surface Mounted on FR4 Board,  $t \le 10$  sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25  $^{\circ}$ C,VDD=50V,VG=10V,L=0.5mH,Rg=25 $\Omega$

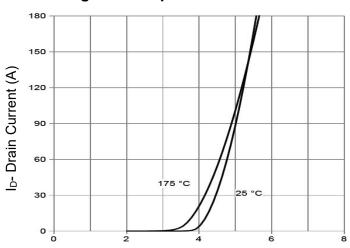


#### **Typical Electrical and Thermal Characteristics**



Vds Drain-Source Voltage (V)





Vgs Gate-Source Voltage (V)

#### **Figure 2 Transfer Characteristics**

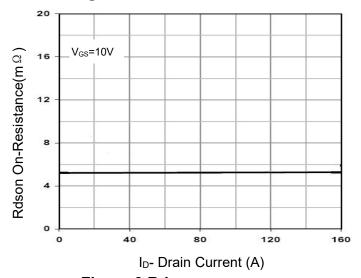
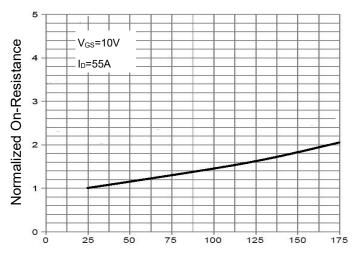
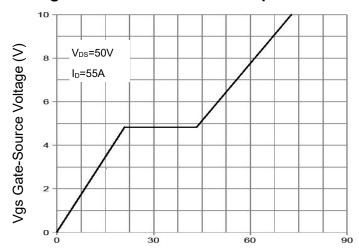


Figure 3 Rdson- Drain Current

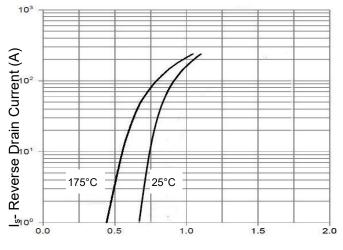


T<sub>J</sub>-Junction Temperature(°C)

#### Figure 4 Rdson-Junction Temperature



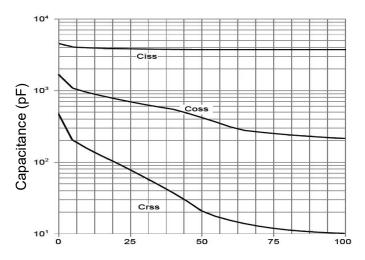
Qg Gate Charge (nC)
Figure 5 Gate Charge

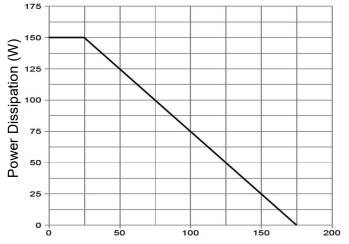


Vsd Source-Drain Voltage (V)

Figure 6 Source- Drain Diode Forward



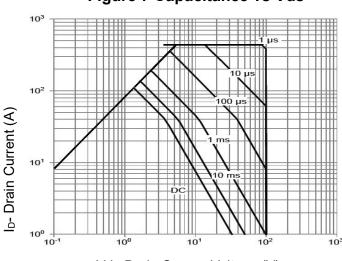


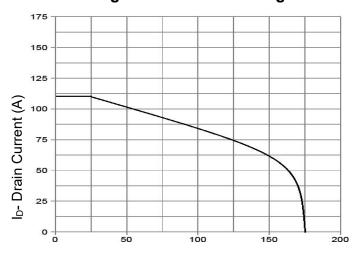


Vds Drain-Source Voltage (V)

Figure 7 Capacitance vs Vds

T<sub>J</sub>-Junction Temperature(°C) **Figure 9 Power De-rating** 





Vds Drain-Source Voltage (V)

Figure 8 Safe Operation Area

T<sub>J</sub>-Junction Temperature (°C)

Figure 10 Current De-rating

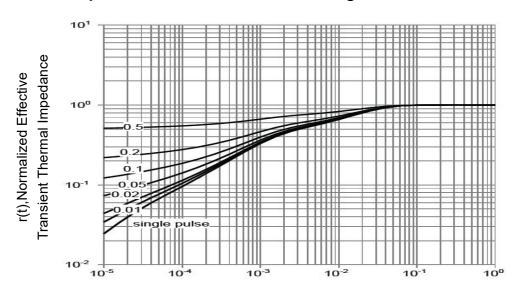
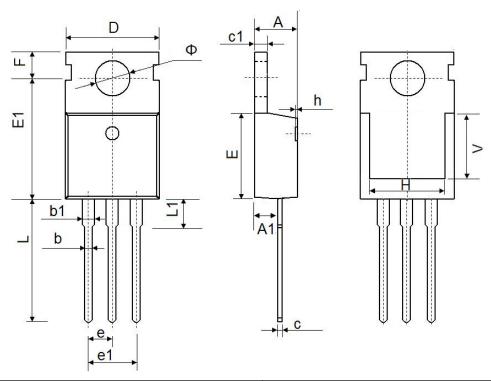


Figure 11 Normalized Maximum Transient Thermal Impedance

Square Wave Pluse Duration(sec)



## **TO-220-3L Package Information**

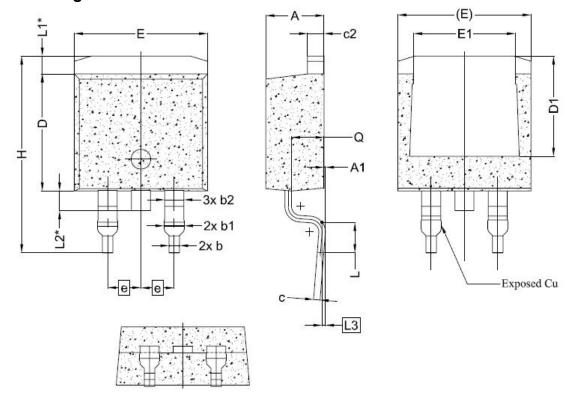


Symbol	Dimensions	In Millimeters	Dimensions In Inches			
Symbol	Min.	Max.	Min.	Max.		
А	4.400	4.600	0.173	0.181		
A1	2.250	2.550	0.089	0.100		
b	0.710	0.910	0.028	0.036		
b1	1.170	1.370	0.046	0.054		
С	0.330	0.650	0.013	0.026		
c1	1.200	1.400	0.047	0.055		
D	9.910	10.250	0.390	0.404		
E	8.9500	9.750	0.352	0.384		
E1	12.650	12.950	0.498	0.510		
е	2.540	2.540 TYP. 0.100 TYP.		2.540 TYP.		TYP.
e1	4.980	5.180	0.196	0.204		
F	2.650	2.950	0.104	0.116		
Н	7.900	8.100	0.311	0.319		
h	0.000	0.300	0.000	0.012		
L	12.900	13.400	0.508	0.528		
L1	2.850	3.250	0.112	0.128		
V	6.900	6.900 REF.		REF.		
Ф	3.400	3.800	0.134	0.150		



# NCEP055N10M, NCEP055N10MD

## **TO-263-2L Package Information**



Symbol	Dimensions In Millimeters			
Symbol	Min.	Nom.	Max.	
A	4.24	4.44	4.64	
A1	0.00	0.10	0.25	
b	0.70	0.80	0.90	
b1	1.20	1.55	1.75	
b2	1.20	1.45	1.70	
С	0.40	0.50	0.60	
c2	1.15	1.27	1.40	
D	8.82	8.92	9.02	
D1	6.86	7.65	-	
E	9.96	10.16	10.36	
E1	6.89	7.77	7.89	
е	2.54BSC			
Н	14.61	15.00	15.88	
L	1.78 2.32		2.79	
L1	1.36 REF.			
L2	1.50 REF.			
L3	0.25 BSC			
Q	2.30	2.48	2.70	



## NCEP055N10M, NCEP055N10MD

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